

## Silicon N-Channel Power MOSFET

### General Description :

HMT59N30, the silicon N-channel Enhanced VDMOSFET, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-3P(N), which accords with the RoHS standard.

### Features :

- Fast Switching
- ESD Improved Capability
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Applications:

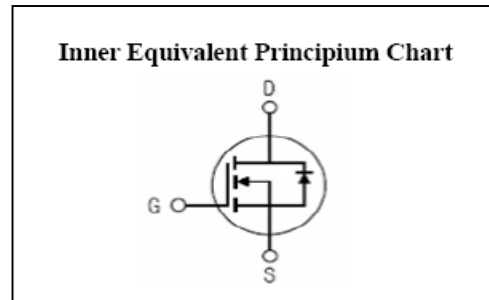
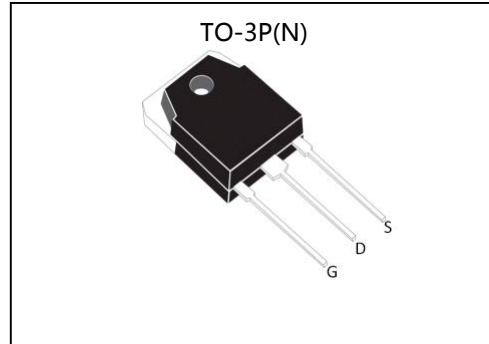
- Power switch circuit of POWER

### Absolute (Tc=25°C unless otherwise specified) :

Symbol	Parameter	Rating	Units
V <sub>DSS</sub>	Drain-to-Source Voltage	300	V
I <sub>D</sub>	Continuous Drain Current	59	A
	Continuous Drain Current T <sub>C</sub> =100 °C	35	A
I <sub>DM</sub> <sup>a1</sup>	Pulsed Drain Current	236	A
V <sub>GS</sub>	Gate-to-Source Voltage	±30	V
E <sub>AS</sub>	Single Pulse Avalanche Energy	3600	mJ
E <sub>AR</sub> <sup>a1</sup>	Avalanche Energy ,Repetitive	300	mJ
I <sub>AR</sub> <sup>a1</sup>	Avalanche Current	59	A
dv/dt <sup>a2</sup>	Peak Diode Recovery dv/dt	5.0	V/ns
P <sub>D</sub>	Power Dissipation	500	W
	Derating Factor above 25°C	4	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range	150 , -55 to 150	°C
T <sub>L</sub>	Maximum Temperature for Soldering	300	°C

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device

V <sub>DSS</sub> (T <sub>C</sub> =150°C)	300	V
I <sub>D</sub>	59	A
P <sub>D</sub> (T <sub>C</sub> =25°C)	500	W
R <sub>DS(ON)TYP</sub>	29	mΩ



## Thermal Characteristics

Symbol	Parameter	Rating	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.25	°C/ W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	40	°C/ W

## Electrical Characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise specified ) :

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$V_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	300	--	--	V
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS}=300V, V_{GS}=0V, T_a=25^\circ\text{C}$	--	--	1.0	$\mu A$
		$V_{DS}=240V, V_{GS}=0V, T_a=125^\circ\text{C}$	--	--	100	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+30V$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-30V$	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=30A$	--	29	36	m $\Omega$
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	--	4.0	V
$g_{fs}$	Forward Trans conductance	$V_{DS}=30V, I_D=30A$	--	55	--	S

Pulse width < 380 $\mu$ s; duty cycle < 2%.

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=25V$ $f=1.0\text{MHz}$	--	5300	--	pF
$C_{oss}$	Output Capacitance		--	730	--	
$C_{rss}$	Reverse Transfer Capacitance		--	80	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=30A, V_{DD}=150V$ $V_{GS}=10V, R_g=25\Omega$	--	160	--	ns
$t_r$	Rise Time		--	560	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	240	--	
$t_f$	Fall Time		--	200	--	
$Q_g$	Total Gate Charge	$I_D=30A, V_{DD}=150V$ $V_{GS}=10V$	--	120	--	nC
$Q_{gs}$	Gate to Source Charge		--	22	--	
$Q_{gd}$	Gate to Drain ( "Miller" ) Charge		--	45	--	

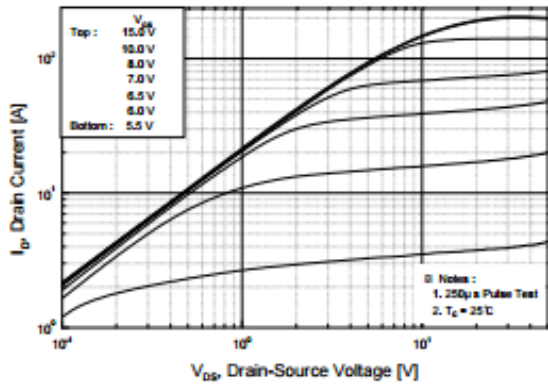
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$I_{SD}$	Continuous Source Current (Body Diode)		--	--	59	A
$I_{SM}$	Maximum Pulsed Current (Body Diode)		--	--	236	A
$V_{SD}$	Diode Forward Voltage	$I_S=30A, V_{GS}=0V$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_S=30A, T_j=25^\circ C$	--	360	--	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_F/dt=100A/\mu s,$ $V_{GS}=0V$	--	7,2	--	$\mu C$

a1 : Repetitive rating; pulse width limited by maximum junction temperature

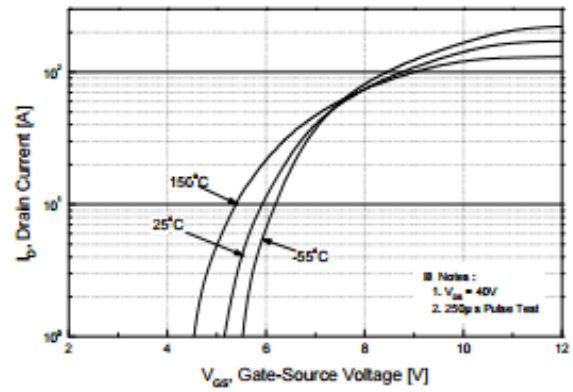
a2 :  $I_{SD}=59A, di/dt \leq 100A/\mu s, V_{DD} \leq BV_{DS},$  Start  $T_j=25^\circ C$

## Characteristics Curve :

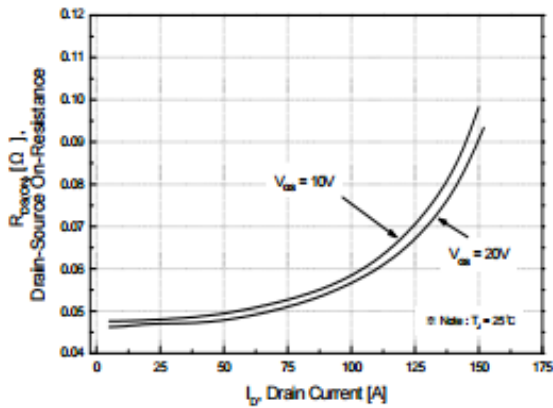
**Figure 1. On-Region Characteristics**



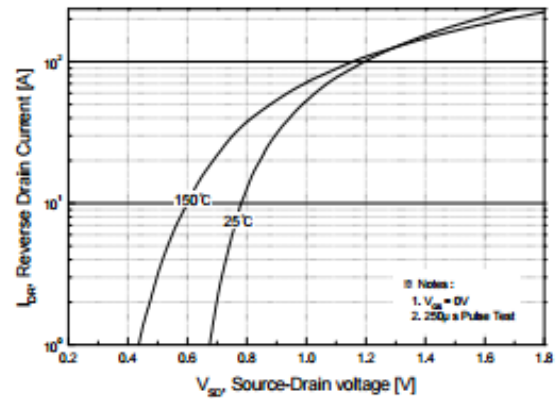
**Figure 2. Transfer Characteristics**



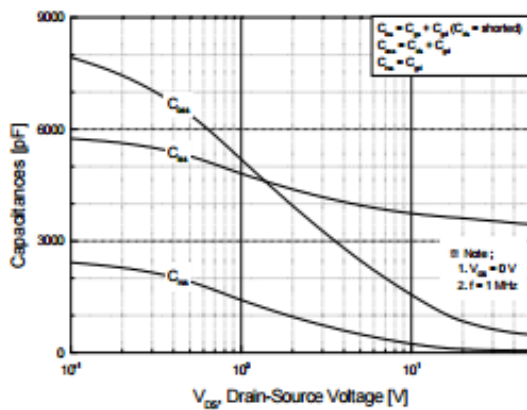
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



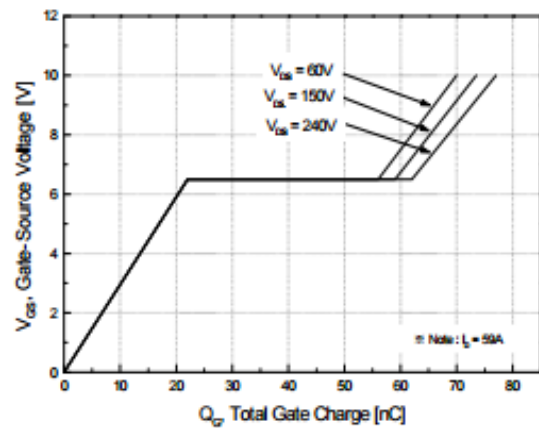
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



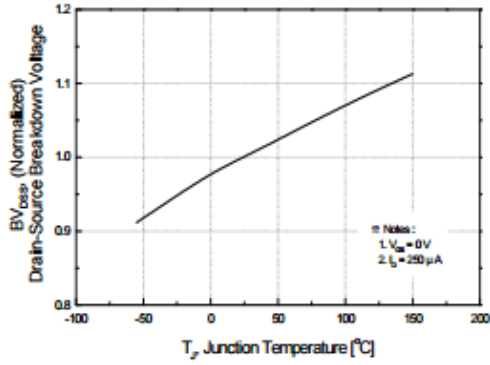
**Figure 5. Capacitance Characteristics**



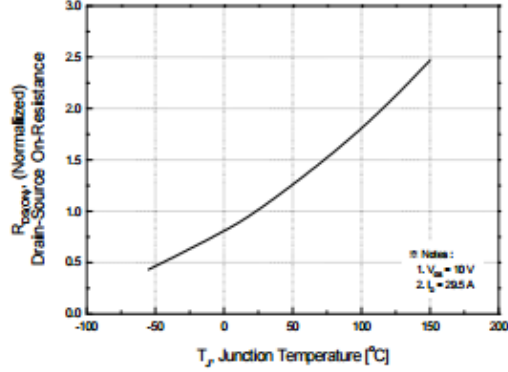
**Figure 6. Gate Charge Characteristics**



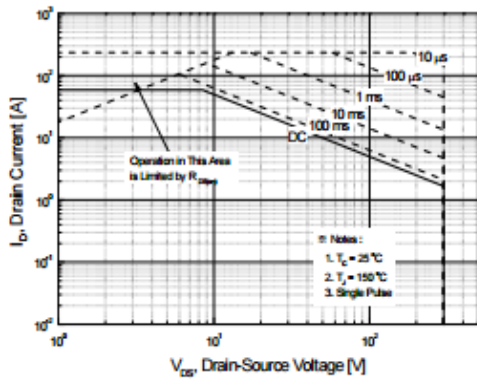
**Figure 7. Breakdown Voltage Variation vs. Temperature**



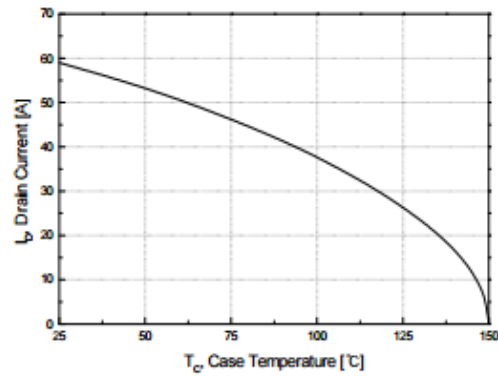
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

